

Special Issue

Innovations in Superconductor and Magnetic Fundamentals, Technologies and Applications

Message from the Guest Editor

The journal is open to receiving submissions on topics covering different aspects of superconductivity and magnetism, their fundamentals, techniques, and applications. It is a great chance for researchers to present their results, to contribute to the understanding of the phenomena, to show their architecture and engineering, and to nurture ideas in this area. The topics of superconductivity, magnetism, and the interaction between these two phenomena are presented in this Special Issue of the journal, combining basic science, state-of-the-art discoveries, and the latest advances in technologies.

Guest Editor

Dr. Luis De Los Santos Valladares

1. Cavendish Laboratory, Department of Physics, University of Cambridge, J.J. Thomson Ave., Cambridge CB3 0HE, UK
2. School of Materials Science and Engineering, Northeastern University, No. 11, Lane 3, Wenhua Road, Heping District, Shenyang 110819, China
3. Laboratorio de Cerámicos y Nanomateriales, Facultad de Ciencias Física, Universidad Nacional Mayor de San Marcos, Ap. Postal, 14-0149 Lima, Perú

Deadline for manuscript submissions

17 October 2025



Inventions

an Open Access Journal
by MDPI

Impact Factor 1.9
CiteScore 4.9



mdpi.com/si/238257

Inventions
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
inventions@mdpi.com

[mdpi.com/journal/
inventions](https://mdpi.com/journal/inventions)





Inventions

an Open Access Journal
by MDPI

Impact Factor 1.9
CiteScore 4.9



[mdpi.com/journal/
inventions](https://mdpi.com/journal/inventions)



About the Journal

Message from the Editorial Board

The unique journal *Inventions* is different from all other journals. Many scholars spend their lives publishing research papers in many different journals, but most of these journals do not help scholars collate and analyze their results or assist in promoting them to a relevant industry. However, *Inventions* will help authors not only to publish their papers in the journal, but also to promote their research results to industry and assist them in realizing the purpose of technology transfer. In the future, *Inventions* will help authors to evaluate their technology license fees based on the valuation theory and approaches and also help authors to show their patents and technologies on a network transaction platform.

Editors-in-Chief

Prof. Dr. Chien-Hung Liu

Department of Mechanical Engineering, National Chung Hsing University, 250 Kuo Kuang Rd., Taichung 402, Taiwan

Prof. Dr. Shouu-Jinn Chang

Department of Electrical Engineering, National Cheng Kung University, Tainan 701, Taiwan

Author Benefits

High Visibility:

indexed within Scopus, ESCI (Web of Science), Inspec, Ei Compendex and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 21.8 days after submission; acceptance to publication is undertaken in 2.9 days (median values for papers published in this journal in the first half of 2025).